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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	54
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s08aw32cpuer

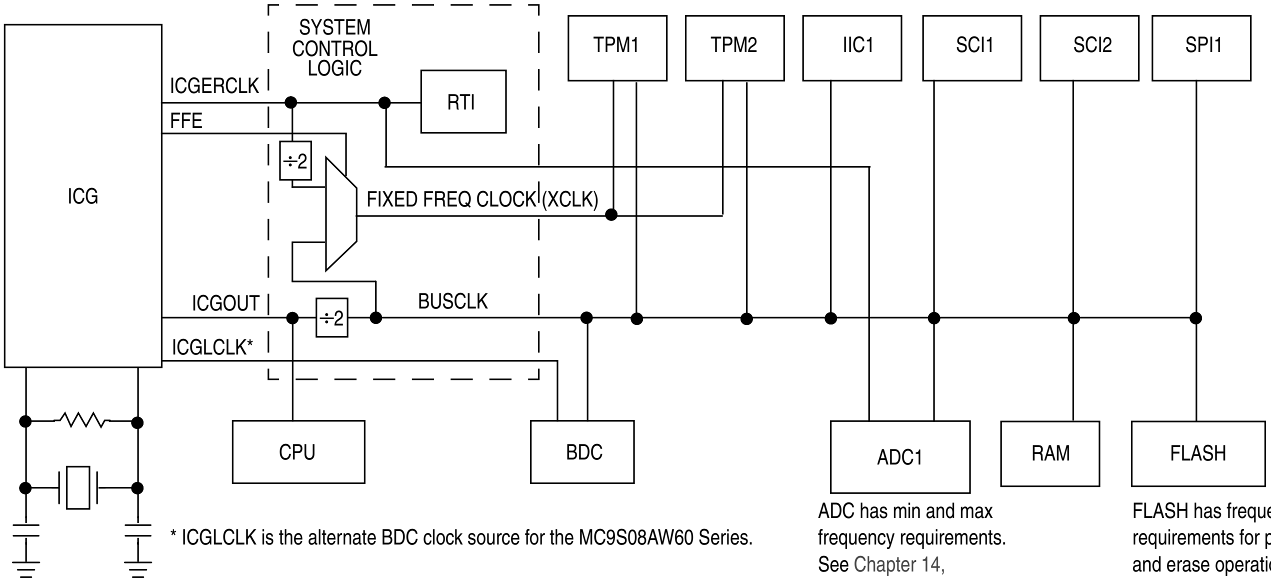
Part Number	Package Description	Original (gold wire) package document number	Current (copper wire) package document number
MC68HC908JW32	48 QFN	98ARH99048A	98ASA00466D
MC9S08AC16			
MC9S908AC60			
MC9S08AC128			
MC9S08AW60			
MC9S08GB60A			
MC9S08GT16A			
MC9S08JM16			
MC9S08JM60			
MC9S08LL16			
MC9S08QE128			
MC9S08QE32			
MC9S08RG60			
MCF51CN128			
MC9RS08LA8	48 QFN	98ARL10606D	98ASA00466D
MC9S08GT16A	32 QFN	98ARH99035A	98ASA00473D
MC9S908QE32	32 QFN	98ARE10566D	98ASA00473D
MC9S908QE8	32 QFN	98ASA00071D	98ASA00736D
MC9S08JS16	24 QFN	98ARL10608D	98ASA00734D
MC9S08QB8			
MC9S08QG8	24 QFN	98ARL10605D	98ASA00474D
MC9S08SH8	24 QFN	98ARE10714D	98ASA00474D
MC9RS08KB12	24 QFN	98ASA00087D	98ASA00602D
MC9S08QG8	16 QFN	98ARE10614D	98ASA00671D
MC9RS08KB12	8 DFN	98ARL10557D	98ASA00672D
MC9S08QG8			
MC9RS08KA2	6 DFN	98ARL10602D	98ASA00735D

Table 1-3 lists the functional versions of the on-chip modules.

Table 1-3. Versions of On-Chip Modules

Module		Version
Analog-to-Digital Converter	(S08ADC10)	1
Internal Clock Generator	(S08ICG)	4
Inter-Integrated Circuit	(S08IIC)	1
Keyboard Interrupt	(S08KBI)	1
Serial Communications Interface	(S08SCI)	2
Serial Peripheral Interface	(S08SPI)	3
Timer Pulse-Width Modulator	(S08TPM)	2
Central Processing Unit	(S08CPU)	2
Debug Module	(DBG)	2

1.3 System Clock Distribution



* ICGLCLK is the alternate BDC clock source for the MC9S08AW60 Series.

ADC has min and max frequency requirements. See Chapter 14, "Analog-to-Digital Converter (S08ADC10V1) and Appendix A, "Electrical Characteristics and Timing Specifications

FLASH has frequency requirements for program and erase operation. See Appendix A, "Electrical Characteristics and Timing Specifications.

Figure 1-2. System Clock Distribution Diagram

Some of the modules inside the MCU have clock source choices. Figure 1-2 shows a simplified clock connection diagram. The ICG supplies the clock sources:

- ICGOUT is an output of the ICG module. It is one of the following:
  - — The external crystal oscillator
  - — An external clock source

4.6.4 FLASH Protection Register (FPROT and NVPROT)

During reset, the contents of the nonvolatile location NVPROT are copied from FLASH into FPROT. This register may be read at any time.

- If FPDIS = 0, then protection can be increased (in other words, a smaller value of FPS can be written).
- If FPDIS = 1, then writes do not change protection.

<table>
<tr><th></th><th>7</th><th>6</th><th>5</th><th>4</th><th>3</th><th>2</th><th>1</th><th>0</th></tr>
<tr><td>R</td><td>FPS7</td><td>FPS6</td><td>FPS5</td><td>FPS4</td><td>FPS3</td><td>FPS2</td><td>FPS1</td><td>FPDIS</td></tr>
<tr><td>W</td><td>(1)</td><td>(1)</td><td>(1)</td><td>(1)</td><td>(1)</td><td>(1)</td><td>(1)</td><td>(1)</td></tr>
<tr><td>Reset</td><td colspan="8">This register is loaded from nonvolatile location NVPROT during reset.</td></tr>
</table>

[1] Background commands can be used to change the contents of these bits in FPROT.

Figure 4-9. FLASH Protection Register (FPROT)

Table 4-11. FPROT Register Field Descriptions

Field	Description
7:1 FPS[7:1]	**FLASH Protect Select Bits** — When FPDIS = 0, this 7-bit field determines the ending address of unprotected FLASH locations at the high address end of the FLASH. Protected FLASH locations cannot be erased or programmed.
0 FPDIS	**FLASH Protection Disable** 0 FLASH block specified by FPS[7:1] is block protected (program and erase not allowed). 1 No FLASH block is protected.

4.6.5 FLASH Status Register (FSTAT)

Bits 3, 1, and 0 always read 0 and writes have no meaning or effect. The remaining five bits are status bits that can be read at any time. Writes to these bits have special meanings that are discussed in the bit descriptions.

<table>
<tr><th></th><th>7</th><th>6</th><th>5</th><th>4</th><th>3</th><th>2</th><th>1</th><th>0</th></tr>
<tr><td>R</td><td rowspan="2">FCBEF</td><td>FCCF</td><td rowspan="2">FPVIOL</td><td rowspan="2">FACCERR</td><td>0</td><td>FBLANK</td><td>0</td><td>0</td></tr>
<tr><td>W</td><td>▨</td><td>▨</td><td>▨</td><td>▨</td><td>▨</td></tr>
<tr><td>Reset</td><td>1</td><td>1</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td></tr>
</table>

▨ = Unimplemented or Reserved

Figure 4-10. FLASH Status Register (FSTAT)

	7	6	5	4	3	2	1	0
R W	PTASE7	PTASE6	PTASE5	PTASE4	PTASE3	PTASE2	PTASE1	PTASE0
Reset	0	0	0	0	0	0	0	0

Figure 6-12. Output Slew Rate Control Enable for Port A (PTASE)

Table 6-5. PTASE Register Field Descriptions

Field	Description
7:0 PTASE[7:0]	**Output Slew Rate Control Enable for Port A Bits** — Each of these control bits determine whether output slew rate control is enabled for the associated PTA pin. For port A pins that are configured as inputs, these bits have no effect. 0 Output slew rate control disabled for port A bit n. 1 Output slew rate control enabled for port A bit n.

	7	6	5	4	3	2	1	0
R W	PTADS7	PTADS6	PTADS5	PTADS4	PTADS3	PTADS2	PTADS1	PTADS0
Reset	0	0	0	0	0	0	0	0

Figure 6-13. Output Drive Strength Selection for Port A (PTASE)

Table 6-6. PTASE Register Field Descriptions

Field	Description
7:0 PTADS[7:0]	**Output Drive Strength Selection for Port A Bits** — Each of these control bits selects between low and high output drive for the associated PTA pin. 0 Low output drive enabled for port A bit n. 1 High output drive enabled for port A bit n.

6.7.14 Port G Pin Control Registers (PTGPE, PTGSE, PTGDS)

In addition to the I/O control, port G pins are controlled by the registers listed below.

	7	6	5	4	3	2	1	0
R W		PTGPE6	PTGPE5	PTGPE4	PTGPE3	PTGPE2	PTGPE1	PTGPE0
Reset	0	0	0	0	0	0	0	0

Figure 6-41. Internal Pullup Enable for Port G Bits (PTGPE)

Table 6-34. PTGPE Register Field Descriptions

Field	Description
6:0 PTGPE[6:0]	**Internal Pullup Enable for Port G Bits** — Each of these control bits determines if the internal pullup device is enabled for the associated PTG pin. For port G pins that are configured as outputs, these bits have no effect and the internal pullup devices are disabled. 0 Internal pullup device disabled for port G bit n. 1 Internal pullup device enabled for port G bit n.

	7	6	5	4	3	2	1	0
R W		PTGSE6	PTGSE5	PTGSE4	PTGSE3	PTGSE2	PTGSE1	PTGSE0
Reset	0	0	0	0	0	0	0	0

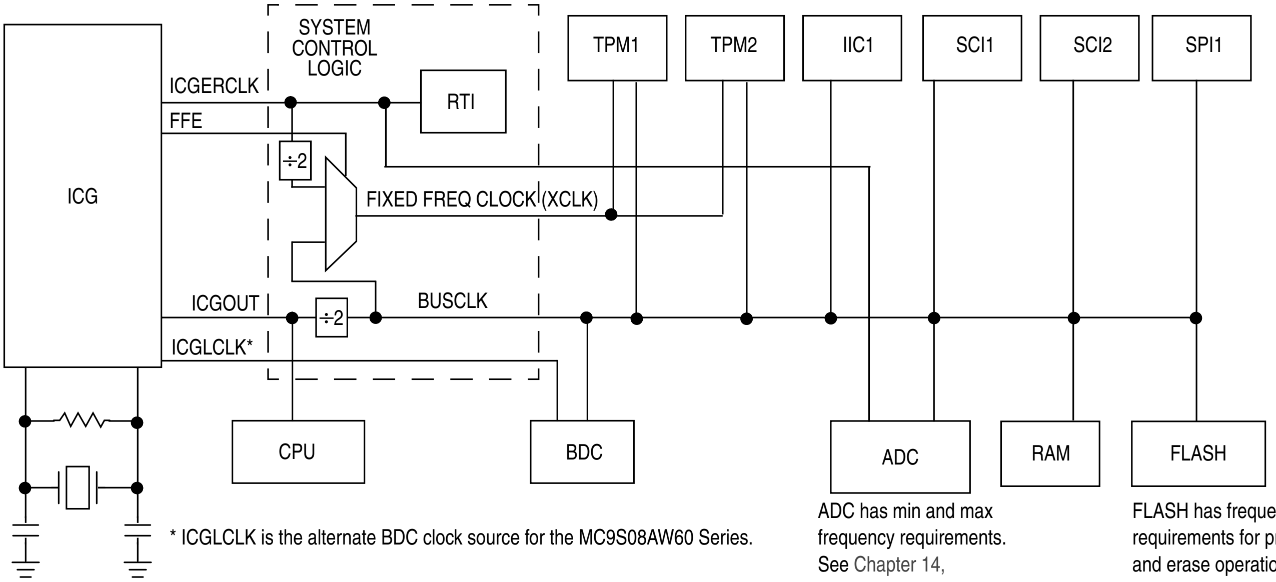
Figure 6-42. Output Slew Rate Control Enable for Port G Bits (PTGSE)

Table 6-35. PTGSE Register Field Descriptions

Field	Description
6:0 PTGSE[6:0]	**Output Slew Rate Control Enable for Port G Bits**— Each of these control bits determine whether output slew rate control is enabled for the associated PTG pin. For port G pins that are configured as inputs, these bits have no effect. 0 Output slew rate control disabled for port G bit n. 1 Output slew rate control enabled for port G bit n.

Chapter 8
Internal Clock Generator (S08ICGV4)

The internal clock generation (ICG) module is used to generate the system clocks for the MC9S08AW60 Series MCU. The analog supply lines V_{DDA} and V_{SSA} are internally derived from the MCU's V_{DD} and V_{SS} pins. Electrical parametric data for the ICG may be found in Appendix A, "Electrical Characteristics and Timing Specifications."



* ICGLCLK is the alternate BDC clock source for the MC9S08AW60 Series.

ADC has min and max frequency requirements. See Chapter 14, "Analog-to-Digital Converter (S08ADC10V1) and Appendix A, "Electrical Characteristics and Timing Specifications

FLASH has frequency requirements for program and erase operation. See Appendix A, "Electrical Characteristics and Timing Specifications.

Figure 8-1. System Clock Distribution Diagram

NOTE

Freescale Semiconductor recommends that FLASH location $FFBE be reserved to store a nonvolatile version of ICGTRM. This will allow debugger and programmer vendors to perform a manual trim operation and store the resultant ICGTRM value for users to access at a later time.

8.4.4 FLL Engaged Internal Unlocked

FEI unlocked is a temporary state that is entered when FEI is entered and the count error (Δn) output from the subtractor is greater than the maximum n_{unlock} or less than the minimum n_{unlock}, as required by the lock detector to detect the unlock condition.

The ICG will remain in this state while the count error (Δn) is greater than the maximum n_{lock} or less than the minimum n_{lock}, as required by the lock detector to detect the lock condition.

In this state the output clock signal ICGOUT frequency is given by $f_{ICGDCLK}$ / R.

8.4.5 FLL Engaged Internal Locked

FLL engaged internal locked is entered from FEI unlocked when the count error (Δn), which comes from the subtractor, is less than n_{lock} (max) and greater than n_{lock} (min) for a given number of samples, as required by the lock detector to detect the lock condition. The output clock signal ICGOUT frequency is given by $f_{ICGDCLK}$ / R. In FEI locked, the filter value is updated only once every four comparison cycles. The update made is an average of the error measurements taken in the four previous comparisons.

8.4.6 FLL Bypassed, External Clock (FBE) Mode

FLL bypassed external (FBE) is entered when any of the following conditions occur:

- From SCM when CLKS = 10 and ERCS is high
- When CLKS = 10, ERCS = 1 upon entering off mode, and off is then exited
- From FLL engaged external mode if a loss of DCO clock occurs and the external reference remains valid (both LOCS = 1 and ERCS = 1)

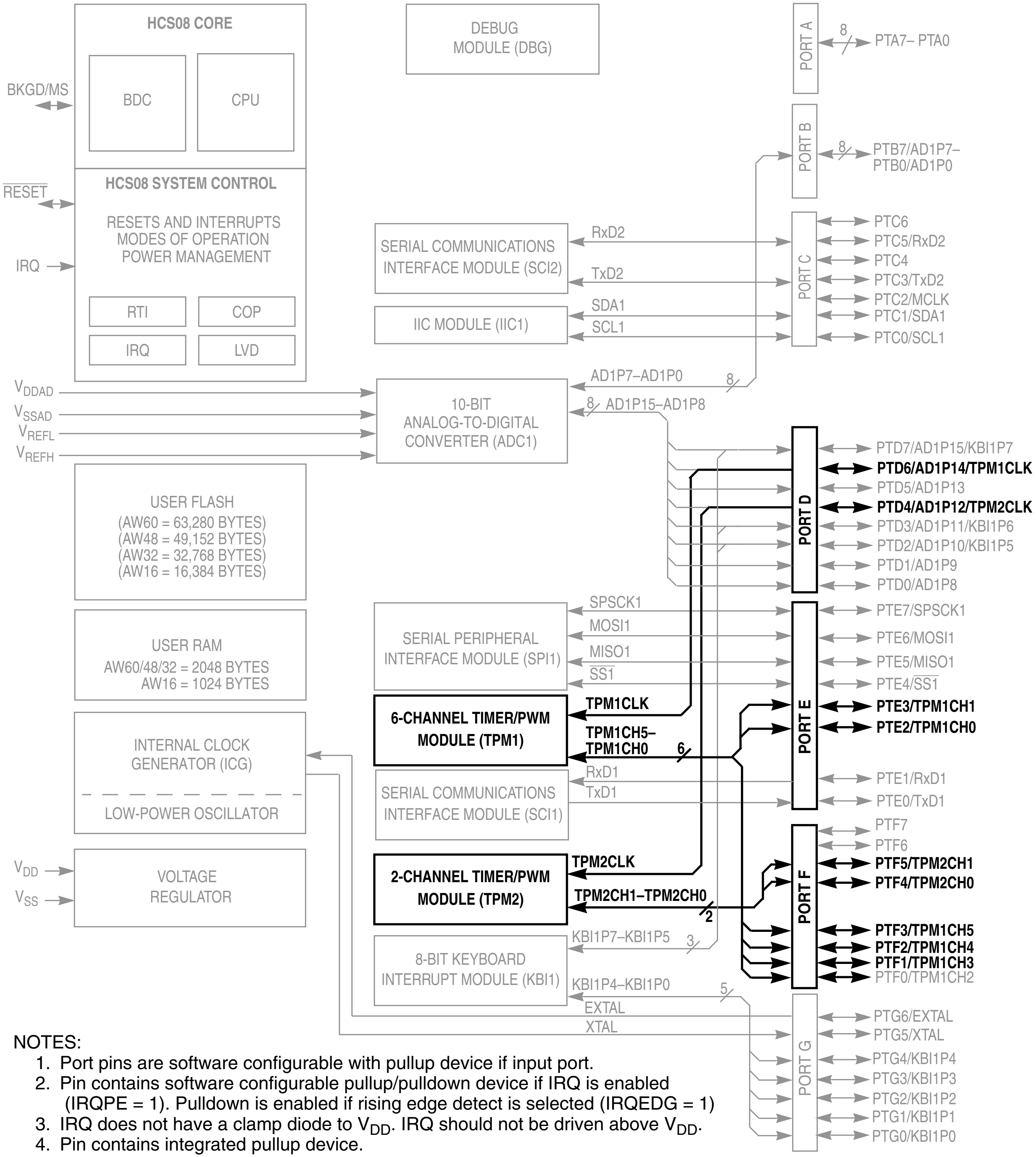
In this state, the DCO and IRG are off and the reference clock is derived from the external reference clock, ICGERCLK. The output clock signal ICGOUT frequency is given by $f_{ICGERCLK}$ / R. If an external clock source is used (REFS = 0), then the input frequency on the EXTAL pin can be anywhere in the range 0 MHz to 40 MHz. If a crystal or resonator is used (REFS = 1), then frequency range is either low for RANGE = 0 or high for RANGE = 1.

8.4.7 FLL Engaged, External Clock (FEE) Mode

The FLL engaged external (FEE) mode is entered when any of the following conditions occur:

- CLKS = 11 and ERCS and DCOS are both high.
- The DCO stabilizes (DCOS = 1) while in SCM upon exiting the off state with CLKS = 11.

In FEE mode, the reference clock is derived from the external reference clock ICGERCLK, and the FLL loop will attempt to lock the ICGDCLK frequency to the desired value, as selected by the MFD bits. To run in FEE mode, there must be a working 32 kHz–100 kHz or 2 MHz–10 MHz external clock source. The maximum external clock frequency is limited to 10 MHz in FEE mode to prevent over-clocking the DCO. The minimum multiplier for the FLL, from Table 8-12 is 4. Because 4 X 10 MHz is 40MHz, which is the operational limit of the DCO, the reference clock cannot be any faster than 10 MHz.



NOTES:
1. Port pins are software configurable with pullup device if input port.
2. Pin contains software configurable pullup/pulldown device if IRQ is enabled (IRQPE = 1). Pulldown is enabled if rising edge detect is selected (IRQEDG = 1)
3. IRQ does not have a clamp diode to V_{DD}. IRQ should not be driven above V_{DD}.
4. Pin contains integrated pullup device.
5. Pins PTD7, PTD3, PTD2, and PTG4 contain both pullup and pulldown devices. Pulldown enabled when KBI is enabled (KBIPEn = 1) and rising edge is selected (KBEDGn = 1).

Figure 10-1. Block Diagram Highlighting the TPM Module

10.5.2.2 Output Compare Mode

With the output compare function, the TPM can generate timed pulses with programmable position, polarity, duration, and frequency. When the counter reaches the value in the channel value registers of an output compare channel, the TPM can set, clear, or toggle the channel pin.

In output compare mode, values are transferred to the corresponding timer channel value registers only after both 8-bit bytes of a 16-bit register have been written. This coherency sequence can be manually reset by writing to the channel status/control register (TPMxCnSC).

An output compare event sets a flag bit (CHnF) that can optionally generate a CPU interrupt request.

10.5.2.3 Edge-Aligned PWM Mode

This type of PWM output uses the normal up-counting mode of the timer counter (CPWMS = 0) and can be used when other channels in the same TPM are configured for input capture or output compare functions. The period of this PWM signal is determined by the setting in the modulus register (TPMxMODH:TPMxMODL). The duty cycle is determined by the setting in the timer channel value register (TPMxCnVH:TPMxCnVL). The polarity of this PWM signal is determined by the setting in the ELSnA control bit. Duty cycle cases of 0 percent and 100 percent are possible.

As Figure 10-11 shows, the output compare value in the TPM channel registers determines the pulse width (duty cycle) of the PWM signal. The time between the modulus overflow and the output compare is the pulse width. If ELSnA = 0, the counter overflow forces the PWM signal high and the output compare forces the PWM signal low. If ELSnA = 1, the counter overflow forces the PWM signal low and the output compare forces the PWM signal high.

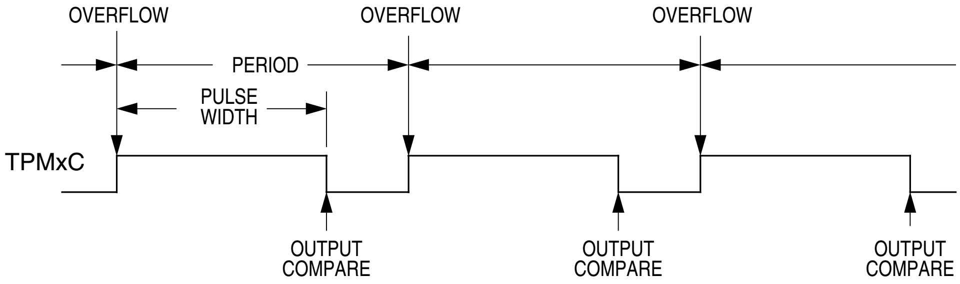


Figure 10-11. PWM Period and Pulse Width (ELSnA = 0)

When the channel value register is set to 0x0000, the duty cycle is 0 percent. By setting the timer channel value register (TPMxCnVH:TPMxCnVL) to a value greater than the modulus setting, 100% duty cycle can be achieved. This implies that the modulus setting must be less than 0xFFFF to get 100% duty cycle.

Because the HCS08 is a family of 8-bit MCUs, the settings in the timer channel registers are buffered to ensure coherent 16-bit updates and to avoid unexpected PWM pulse widths. Writes to either register, TPMxCnVH or TPMxCnVL, write to buffer registers. In edge-PWM mode, values are transferred to the corresponding timer channel registers only after both 8-bit bytes of a 16-bit register have been written and the value in the TPMxCNTH:TPMxCNTL counter is 0x0000. (The new duty cycle does not take effect until the next full period.)

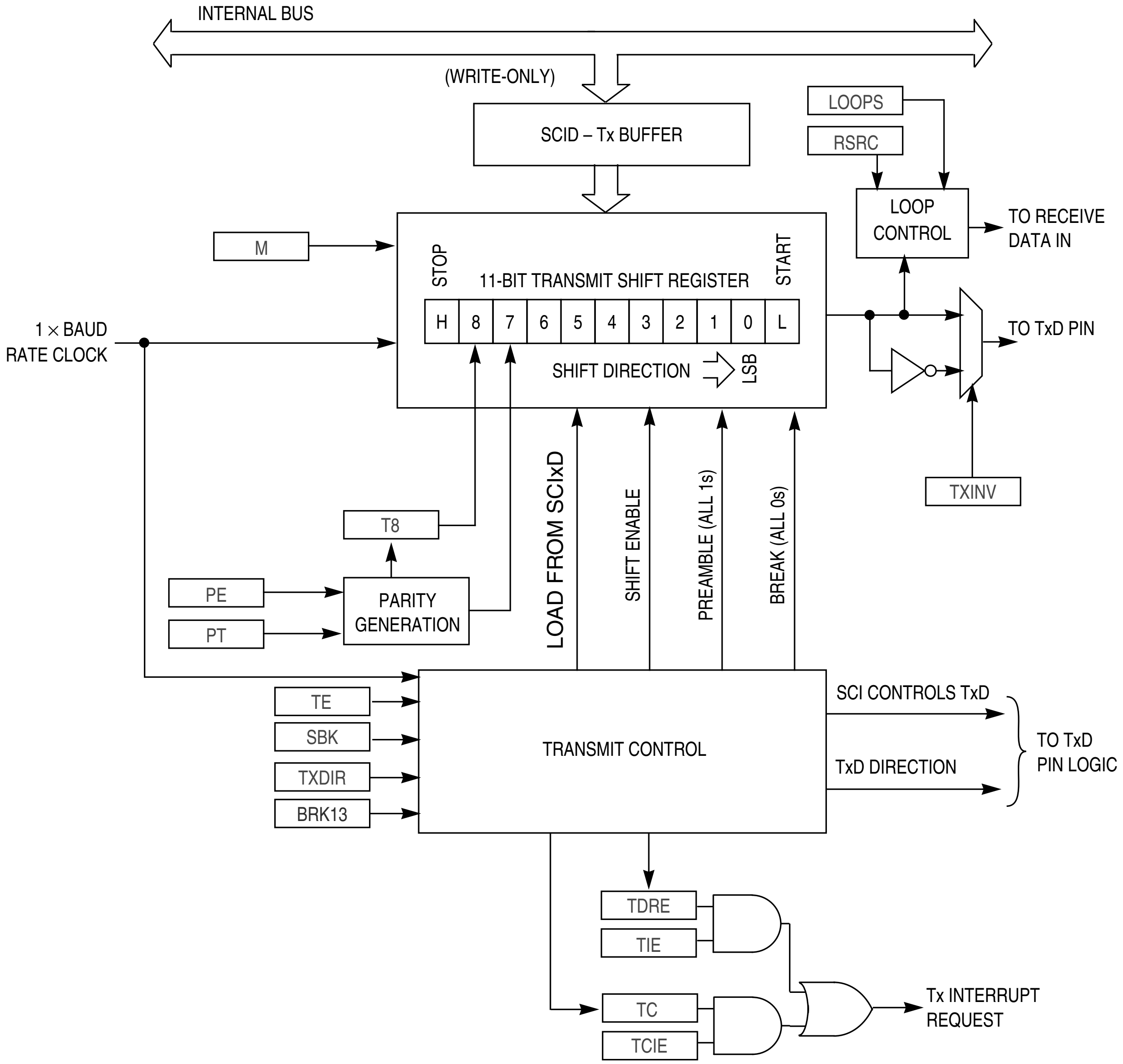


Figure 11-2. SCI Transmitter Block Diagram

Refer to the direct-page register summary in the Memory chapter of this data sheet for the absolute address assignments for all SCI registers. This section refers to registers and control bits only by their names. A Freescale-provided equate or header file is used to translate these names into the appropriate absolute addresses.

11.2.1 SCI Baud Rate Registers (SCIxBDH, SCIxBHL)

This pair of registers controls the prescale divisor for SCI baud rate generation. To update the 13-bit baud rate setting [SBR12:SBR0], first write to SCIxBDH to buffer the high half of the new value and then write to SCIxBDL. The working value in SCIxBDH does not change until SCIxBDL is written.

SCIxBDL is reset to a non-zero value, so after reset the baud rate generator remains disabled until the first time the receiver or transmitter is enabled (RE or TE bits in SCIxC2 are written to 1).

	7	6	5	4	3	2	1	0
R	0	0	0	SBR12	SBR11	SBR10	SBR9	SBR8
W	▨	▨	▨					
Reset	0	0	0	0	0	0	0	0

▨ = Unimplemented or Reserved

Figure 11-4. SCI Baud Rate Register (SCIxBDH)

Table 11-1. SCIxBDH Register Field Descriptions

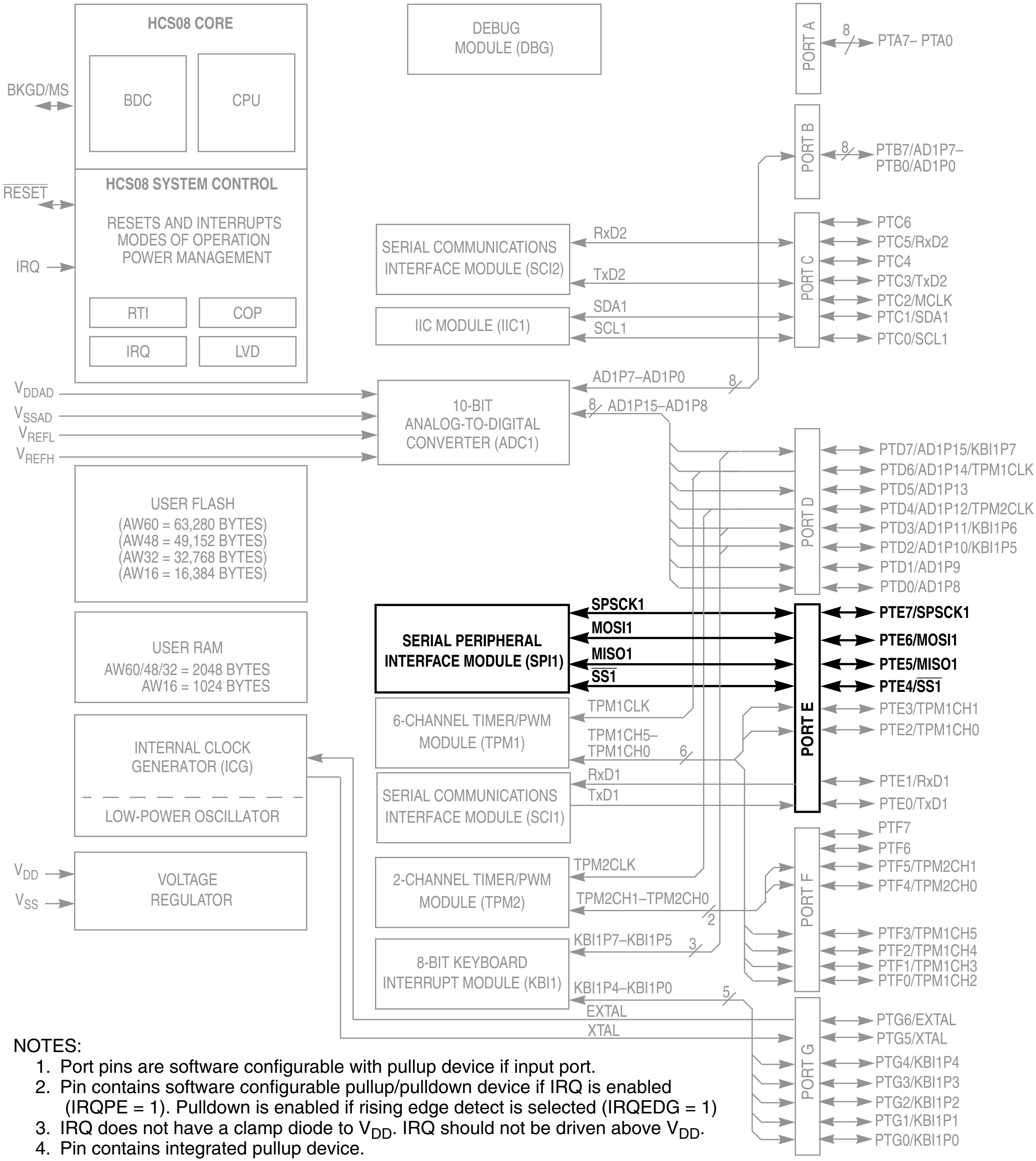
Field	Description
4:0 SBR[12:8]	**Baud Rate Modulo Divisor** — These 13 bits are referred to collectively as BR, and they set the modulo divide rate for the SCI baud rate generator. When BR = 0, the SCI baud rate generator is disabled to reduce supply current. When BR = 1 to 8191, the SCI baud rate = BUSCLK/(16×BR). See also BR bits in Table 11-2.

	7	6	5	4	3	2	1	0
R	SBR7	SBR6	SBR5	SBR4	SBR3	SBR2	SBR1	SBR0
W								
Reset	0	0	0	0	0	1	0	0

Figure 11-5. SCI Baud Rate Register (SCIxBDL)

Table 11-2. SCIxBDL Register Field Descriptions

Field	Description
4:0 SBR[12:8]	**Baud Rate Modulo Divisor** — These 13 bits are referred to collectively as BR, and they set the modulo divide rate for the SCI baud rate generator. When BR = 0, the SCI baud rate generator is disabled to reduce supply current. When BR = 1 to 8191, the SCI baud rate = BUSCLK/(16×BR). See also BR bits in Table 11-1.



NOTES:

1. Port pins are software configurable with pullup device if input port.
2. Pin contains software configurable pullup/pulldown device if IRQ is enabled (IRQPE = 1). Pulldown is enabled if rising edge detect is selected (IRQEDG = 1)
3. IRQ does not have a clamp diode to V_{DD}. IRQ should not be driven above V_{DD}.
4. Pin contains integrated pullup device.
5. Pins PTD7, PTD3, PTD2, and PTG4 contain both pullup and pulldown devices. Pulldown enabled when KBI is enabled (KBIPEn = 1) and rising edge is selected (KBEDGn = 1).

Figure 12-1. Block Diagram Highlighting the SPI Module

in LSBFE. Both variations of SPSCK polarity are shown, but only one of these waveforms applies for a specific transfer, depending on the value in CPOL. The SAMPLE IN waveform applies to the MOSI input of a slave or the MISO input of a master. The MOSI waveform applies to the MOSI output pin from a master and the MISO waveform applies to the MISO output from a slave. The $\overline{\text{SS}}$ OUT waveform applies to the slave select output from a master (provided MODFEN and SSOE = 1). The master $\overline{\text{SS}}$ output goes to active low at the start of the first bit time of the transfer and goes back high one-half SPSCK cycle after the end of the eighth bit time of the transfer. The $\overline{\text{SS}}$ IN waveform applies to the slave select input of a slave.

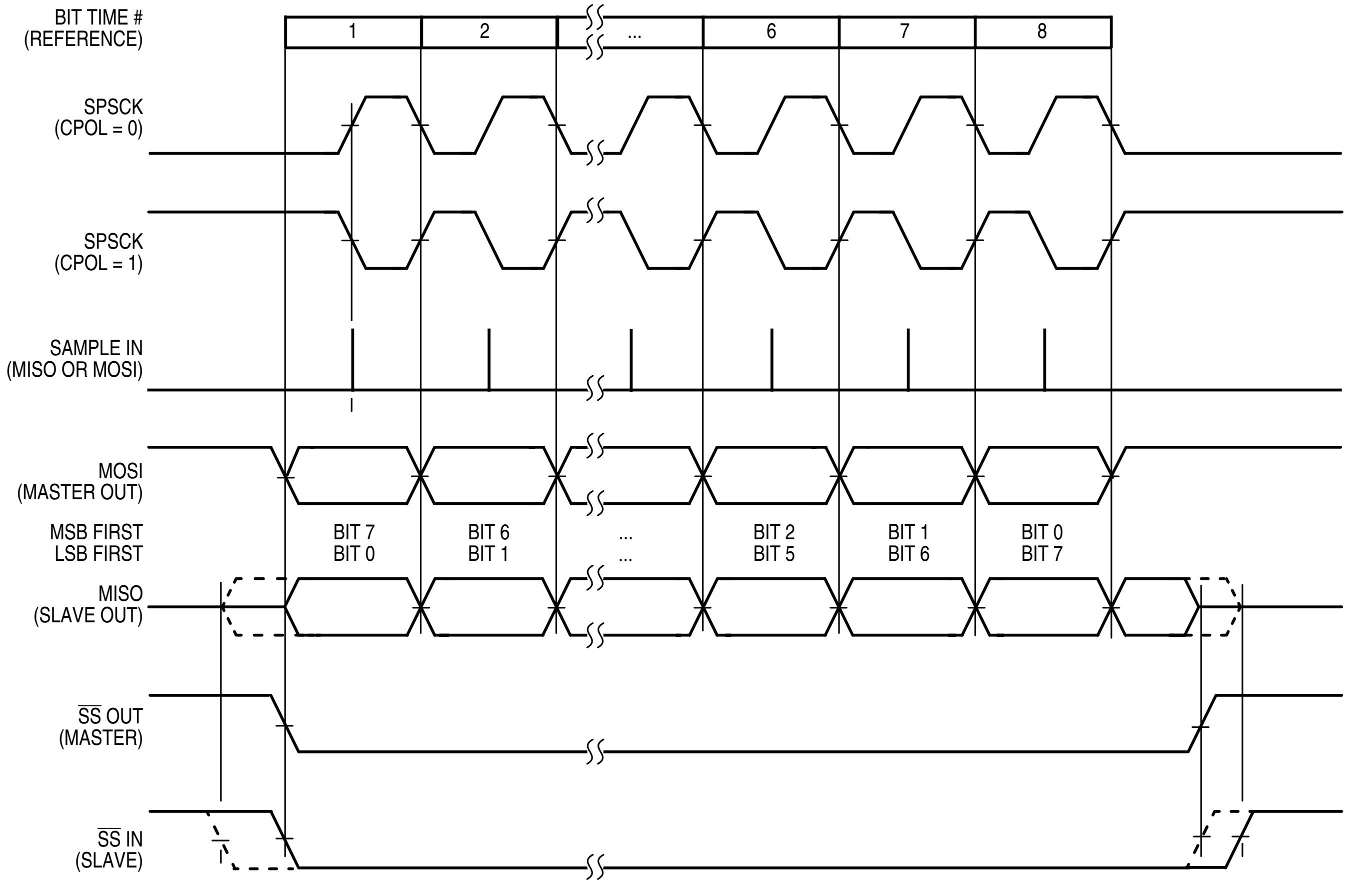


Figure 12-11. SPI Clock Formats (CPHA = 0)

When CPHA = 0, the slave begins to drive its MISO output with the first data bit value (MSB or LSB depending on LSBFE) when $\overline{\text{SS}}$ goes to active low. The first SPSCK edge causes both the master and the slave to sample the data bit values on their MISO and MOSI inputs, respectively. At the second SPSCK edge, the SPI shifter shifts one bit position which shifts in the bit value that was just sampled and shifts the second data bit value out the other end of the shifter to the MOSI and MISO outputs of the master and slave, respectively. When CPHA = 0, the slave's $\overline{\text{SS}}$ input must go to its inactive high level between transfers.

13.3.5 IIC Data I/O Register (IIC1D)

	7	6	5	4	3	2	1	0
R	DATA							
W								
Reset	0	0	0	0	0	0	0	0

Figure 13-7. IIC Data I/O Register (IIC1D)

Table 13-6. IIC1D Register Field Descriptions

Field	Description
7:0 DATA	**Data** — In master transmit mode, when data is written to the IIC1D, a data transfer is initiated. The most significant bit is sent first. In master receive mode, reading this register initiates receiving of the next byte of data.

NOTE

When transmitting out of master receive mode, the IIC mode should be switched before reading the IIC1D register to prevent an inadvertent initiation of a master receive data transfer.

In slave mode, the same functions are available after an address match has occurred.

Note that the TX bit in IIC1C must correctly reflect the desired direction of transfer in master and slave modes for the transmission to begin. For instance, if the IIC is configured for master transmit but a master receive is desired, then reading the IIC1D will not initiate the receive.

Reading the IIC1D will return the last byte received while the IIC is configured in either master receive or slave receive modes. The IIC1D does not reflect every byte that is transmitted on the IIC bus, nor can software verify that a byte has been written to the IIC1D correctly by reading it back.

In master transmit mode, the first byte of data written to IIC1D following assertion of MST is used for the address transfer and should comprise of the calling address (in bit 7–bit 1) concatenated with the required R/W bit (in position bit 0).

13.6.1 Byte Transfer Interrupt

The TCF (transfer complete flag) bit is set at the falling edge of the 9th clock to indicate the completion of byte transfer.

13.6.2 Address Detect Interrupt

When the calling address matches the programmed slave address (IIC address register), the IAAS bit in the status register is set. The CPU is interrupted provided the IICIE is set. The CPU must check the SRW bit and set its Tx mode accordingly.

13.6.3 Arbitration Lost Interrupt

The IIC is a true multi-master bus that allows more than one master to be connected on it. If two or more masters try to control the bus at the same time, the relative priority of the contending masters is determined by a data arbitration procedure. The IIC module asserts this interrupt when it loses the data arbitration process and the ARBL bit in the status register is set.

Arbitration is lost in the following circumstances:

- SDA sampled as a low when the master drives a high during an address or data transmit cycle.
- SDA sampled as a low when the master drives a high during the acknowledge bit of a data receive cycle.
- A START cycle is attempted when the bus is busy.
- A repeated START cycle is requested in slave mode.
- A STOP condition is detected when the master did not request it.

This bit must be cleared by software by writing a one to it.

15.1.1 Features

Features of the BDC module include:

- Single pin for mode selection and background communications
- BDC registers are not located in the memory map
- SYNC command to determine target communications rate
- Non-intrusive commands for memory access
- Active background mode commands for CPU register access
- GO and TRACE1 commands
- BACKGROUND command can wake CPU from stop or wait modes
- One hardware address breakpoint built into BDC
- Oscillator runs in stop mode, if BDC enabled
- COP watchdog disabled while in active background mode

Features of the ICE system include:

- Two trigger comparators: Two address + read/write (R/W) or one full address + data + R/W
- Flexible 8-word by 16-bit FIFO (first-in, first-out) buffer for capture information:
  - Change-of-flow addresses or
  - Event-only data
- Two types of breakpoints:
  - Tag breakpoints for instruction opcodes
  - Force breakpoints for any address access
- Nine trigger modes:
  - Basic: A-only, A OR B
  - Sequence: A then B
  - Full: A AND B data, A AND NOT B data
  - Event (store data): Event-only B, A then event-only B
  - Range: Inside range (A ≤ address ≤ B), outside range (address < A or address > B)

15.2 Background Debug Controller (BDC)

All MCUs in the HCS08 family contain a single-wire background debug interface that supports in-circuit programming of on-chip nonvolatile memory and sophisticated non-intrusive debug capabilities. Unlike debug interfaces on earlier 8-bit MCUs, this system does not interfere with normal application resources. It does not use any user memory or locations in the memory map and does not share any on-chip peripherals.

BDC commands are divided into two groups:

- Active background mode commands require that the target MCU is in active background mode (the user program is not running). Active background mode commands allow the CPU registers to be read or written, and allow the user to trace one user instruction at a time, or GO to the user program from active background mode.

15.4.3.7 Debug Control Register (DBGC)

This register can be read or written at any time.

	7	6	5	4	3	2	1	0
R W	DBGEN	ARM	TAG	BRKEN	RWA	RWAEN	RWB	RWBEN
Reset	0	0	0	0	0	0	0	0

Figure 15-7. Debug Control Register (DBGC)

Table 15-4. DBGC Register Field Descriptions

Field	Description
7 DBGEN	**Debug Module Enable** — Used to enable the debug module. DBGEN cannot be set to 1 if the MCU is secure. 0 DBG disabled 1 DBG enabled
6 ARM	**Arm Control** — Controls whether the debugger is comparing and storing information in the FIFO. A write is used to set this bit (and ARMF) and completion of a debug run automatically clears it. Any debug run can be manually stopped by writing 0 to ARM or to DBGEN. 0 Debugger not armed 1 Debugger armed
5 TAG	**Tag/Force Select** — Controls whether break requests to the CPU will be tag or force type requests. If BRKEN = 0, this bit has no meaning or effect. 0 CPU breaks requested as force type requests 1 CPU breaks requested as tag type requests
4 BRKEN	**Break Enable** — Controls whether a trigger event will generate a break request to the CPU. Trigger events can cause information to be stored in the FIFO without generating a break request to the CPU. For an end trace, CPU break requests are issued to the CPU when the comparator(s) and R/W meet the trigger requirements. For a begin trace, CPU break requests are issued when the FIFO becomes full. TRGSEL does not affect the timing of CPU break requests. 0 CPU break requests not enabled 1 Triggers cause a break request to the CPU
3 RWA	**R/W Comparison Value for Comparator A** — When RWAEN = 1, this bit determines whether a read or a write access qualifies comparator A. When RWAEN = 0, RWA and the R/W signal do not affect comparator A. 0 Comparator A can only match on a write cycle 1 Comparator A can only match on a read cycle
2 RWAEN	**Enable R/W for Comparator A** — Controls whether the level of R/W is considered for a comparator A match. 0 R/W is not used in comparison A 1 R/W is used in comparison A
1 RWB	**R/W Comparison Value for Comparator B** — When RWBEN = 1, this bit determines whether a read or a write access qualifies comparator B. When RWBEN = 0, RWB and the R/W signal do not affect comparator B. 0 Comparator B can match only on a write cycle 1 Comparator B can match only on a read cycle
0 RWBEN	**Enable R/W for Comparator B** — Controls whether the level of R/W is considered for a comparator B match. 0 R/W is not used in comparison B 1 R/W is used in comparison B

A.6 DC Characteristics

This section includes information about power supply requirements, I/O pin characteristics, and power supply current in various operating modes.

Table A-6. MCU Operating Conditions

Characteristic	Min	Typ	Max	Unit
Supply Voltage	2.7	—	5.5	V
Temperature				°C
M	–40	—	125	
V	–40	—	105	
C	-40	—	85	

Table A-7. DC Characteristics

Num	C	Parameter	Symbol	Min	Typ[1]	Max	Unit
1	P	Output high voltage — Low Drive (PTxDSn = 0)	V_{OH}				V
		5 V, I_{Load} = –2 mA		V_{DD} – 1.5	—	—	
		3 V, I_{Load} = –0.6 mA		V_{DD} – 1.5	—	—	
		5 V, I_{Load} = –0.4 mA		V_{DD} – 0.8	—	—	
		3 V, I_{Load} = –0.24 mA		V_{DD} – 0.8	—	—	
		Output high voltage — High Drive (PTxDSn = 1)					
		5 V, I_{Load} = –10 mA		V_{DD} – 1.5	—	—	
		3 V, I_{Load} = –3 mA		V_{DD} – 1.5	—	—	
		5 V, I_{Load} = –2 mA		V_{DD} – 0.8	—	—	
		3 V, I_{Load} = –0.4 mA		V_{DD} – 0.8	—	—	
2	P	Output low voltage — Low Drive (PTxDSn = 0)	V_{OL}				V
		5 V, I_{Load} = 2 mA		—	—	1.5	
		3 V, I_{Load} = 0.6 mA		—	—	1.5	
		5 V, I_{Load} = 0.4 mA		—	—	0.8	
		3 V, I_{Load} = 0.24 mA		—	—	0.8	
		Output low voltage — High Drive (PTxDSn = 1)					
		5 V, I_{Load} = 10 mA		—	—	1.5	
		3 V, I_{Load} = 3 mA		—	—	1.5	
		5 V, I_{Load} = 2 mA		—	—	0.8	
		3 V, I_{Load} = 0.4 mA		—	—	0.8	
3	D	Output high current — Max total I_{OH} for all ports	I_{OHT}				mA
		5V		—	—	100	
		3V		—	—	60	
4	D	Output low current — Max total I_{OL} for all ports	I_{OLT}				mA
		5V		—	—	100	
		3V		—	—	60	
5	P	Input high voltage; all digital inputs	V_{IH}	0.65 x V_{DD}	—	—	V
6	P	Input low voltage; all digital inputs	V_{IL}	—	—	0.35 x V_{DD}	
7	T	Input hysteresis; all digital inputs	V_{hys}	0.06 x V_{DD}			mV
8	P	Input leakage current; input only pins[2]	$\|I_{In}\|$	—	0.01	1	µA